Nama	Multilayer Chip Inductors	СОМРОІ	NENT SPECIFICATION	1/
Name	MLI-160808	SPEC#	MLI-160808-4R7M	/ 8

#### 1. Scope

This specification applies to the MLI-1608 series Multilayer Chip Inductors

### 2. Standard and Atmospheric Conditions

Unless otherwise specified the standard range of atmospheric conditions for making measurements and tests is as follows:

Ambient temperature : 20±15°C Relative humidity : 30~70%

If there may be any doubt on the results, measurements shall be made within

the following limits:

Ambient temperature : 25±5°C Relative humidity : 30~70%

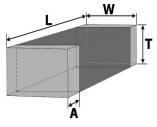
#### 3. Ratings

	INDUCTANCE		SELF-RESONANT	DC RESISTANCE	*
PART NO	INDOCTANCE	Q	FREQUENCY(MHz)	DO RESISTANCE	RATED CURRENT
	AT10 MHz 100mV	Min	Min	$(\Omega)$ Max	(mA)Max
MLI-160808 <b>-</b> 4R7M	4.7µH±10%	35	33	2.1	15

<sup>※</sup>The maximum rated current is measured at ambient temperature increasing to 40 °C within 2 hours.

Regarding to the inductance variability of rated current, please refer to page 2: Inductance Vs. DC superposition characteristics.

#### 4. Dimensions



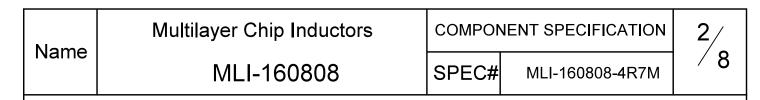
unit: mm (inch) OPERATING TEMP. RANGE:  $-55^{\circ}$ C ~ +125°C STORAGE TEMP. RANGE:  $-40^{\circ}$ C ~ +85°C

0.0.0.0				<b>33</b> C	
TYPE	L	W	Т	A(m/m)	
MLI-1608	1.6±0.15	0.8±0.15	0.8±0.15	0.2~0.6	
	(0.063±0.006)	(0.031±0.006)	(0.031±0.006)	(0.008~0.024)	

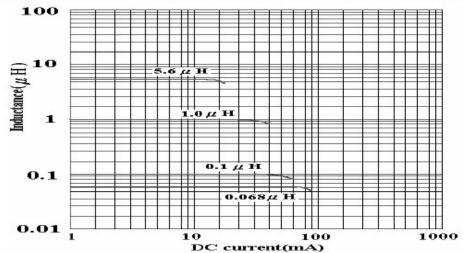
# 5. The Place of Origin:

#### Taiwan

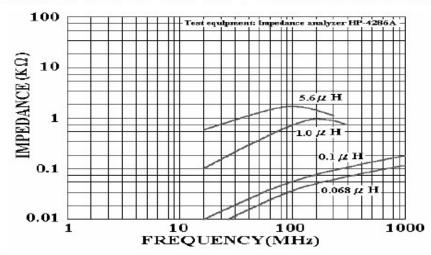
PLANNED BY	CHECKED BY	APPROVED BY	
Marco	Lun	Tina	鈺鎧文件中心 發行章



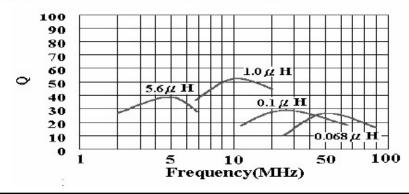
## INDUCTANCE VS DC SUPERPOSITION CHARACTERISTICS



#### IMPEDANCE VS FREQUENCY CHARACTERISTICS



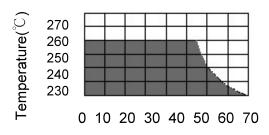
## **Q VS FREQUENCY CHARACTERISTICS**



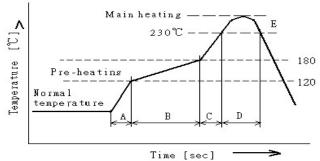
Name Multilayer Chip Inductors COMPONENT SPECIFICATION 3/8

### 6. Reflow soldering conditions

- Pre—heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150°C max. Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100°C max.
   Insufficient pre—heating may cause cracks on the ferrite, resulting in the deterioration of product quality.
- Products should be soldered within the following allowable range indicated by the slanted line. The excessive soldering conditions may cause the corrosion of the electrode, when soldering is repeated, allowable time is the accumulated time.



#### Temperature Profile



Α	Slope of temp. rise	1 to 5	°C/sec
В	Heat time	50 to 150	sec
Ь	Heat temperature	120 to 180	$^{\circ}\!\mathbb{C}$
С	Slope of temp. rise	1 to 5	°C/sec
D	Time over 230℃	90~120	sec
Е	Peak temperature	255~260	$^{\circ}\!\mathbb{C}$
	Peak hold time	10 max.	sec
	No. of mounting	3	times

(Melting area of solder)

6-1 Reworking with soldering iron

Preheating	150℃, 1 minute
Tip temperature	280°ℂ max.
Soldering time	3 seconds max.
Soldering iron output	30w max.
End of soldering iron	φ 3mm max.

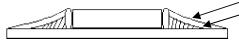
• Reworking should be limited to only one time.

Note: Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the ferrite material due to the thermal shock.

6-2 Solder Volume

Solder shall be used not to be exceed the upper limits as shown below.

Upper Limit
Recommendable



When solder volume is increased, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.

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# 7. Equipment

7-1 Inductance

Inductance shall be measured with HP-4286A Inductance analyzer or equivalent system

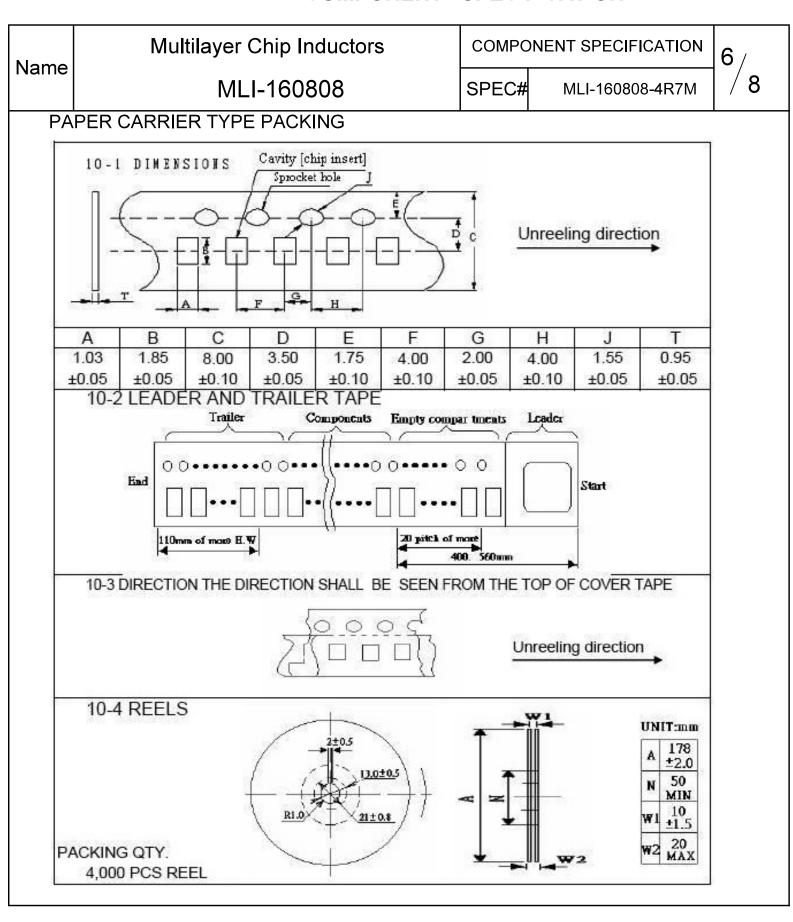
7-2 DC RESISTANCE

DC resistance shall be measured using HP 4338 digital mili—ohm meter with 4 terminal method.

#### 8. Mechanical Characteristics

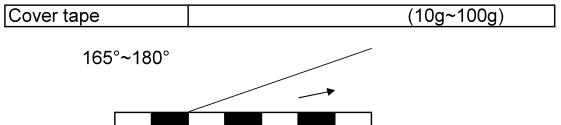
ITEM	Specification	Test Conditions
Terminal	Terminal strength does not distort	Solder chip on PCB and applied 10N
Strength	the case shall meet SPEC DC	(1.02Kgf) for 10 sec
	resistance specifications.	CHIP
		Close Spare PCS
Substrate	SPEC substrate bending test DC	After soldering a chip to a test substrate,
Bending Test	resistance shall meet	bend the substrate by 3mm hold for 10s
_	specifications.	land then return.
		Soldering shall be done in accordance
		with the recommended PC board pattern
		and reflow soldering.
		unit : mm  45 45 100
Resistance	No visible damage	Solder Temp. : 265±3°C
to Solder Heat	Electrical characteristics and mechanic	Immersion time : 6±1 sec
	characteristics shall be satisfied.	Preheating : 100℃ to 150℃, 1 minute.
		Measurement to be made after keeping at room
	Consult standard MIL-STD-202	temp for 24±2 hrs.
	METHOD 210	Solder : Sn-3Ag-0.5Cu
Solderability	95% min. coverage of all	Solder temp. : 240±5°C
	metabolised area	Immersion time: 3±1 sec
	Consult standard J-STD-002	

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9.	RELIABILITY AND TEST CONDITIONS 9-1 HIGH TEMPERATURE RESISTANCE a. Performance specification 1.Appearance: no mechanical damage 2.Inductance shall be with ±20% of the initial value. b.Test condition 1.Temperature: 125°C ±2°C 2.Testing time: 1000±12hrs 3.Measurement: After placing at room ambient to 1000±12hrs 3.Measurement: After placing at room ambient to 1000±12hrs 3.Measurement: After placing at room ambient to 1000±12hrs 3.Measurement: no mechanical damage 2.Inductance shall be with ±20% of the initial value. b.Test condition 1.Humidity: 85 ± 5%RH 2. Temperature: 85°C ±2°C 3.Testing time: 1000 ± 12 hours 4.Measurement: After placing at room ambient to 1000±12 hours 4.Measurement: After placing at room ambient to 1000±12 hours 4.Measurement: After placing damage 2.Inductance shall be with ±20% of the initial value. b.Test condition 1. Low Temperature: -55°C ±5°C kept stabilized 2. High Temperature: 125°C ±5°C kept stabilized 3.Measurement: After placing for 24hours mininue. 4. step155°C temp±5°C 30±3 minutes	remperature for semperature fo	r 24 hours minimum each each	1
	step2. Room temperature 2to5 minutes step3. +125°C temp±5°C 30±3 minutes step4. room temperature 2to5 minutes 9-4 VIBRATION TEST			
	a.Performance specification 1.Appearance: no mechanical damage 2.Inductance shall be with ±20% of the initial value. b.Test condition 1.Frequency and Amplitude:10-2000-10Hz 2.Direction:X,Y,Z. 3.Test duration:4 hours for each direction,12hour. 9-5 Mechanical Shock TEST a.Performance specification 1.Appearance: no mechanical damage 2.Inductance shall be with ±20% of the initial value.	rs in total.		
	b.Test condition 1.peak acceleration : 100 g's 2.Duration of pulse : 6 ms 3.Waveform : Half-sine 4.Velocity change : 12.3 ft/sec 5. Direction : X , Y , Z ( 3axes/3 times ) 9-6 Operational Life			
	a. Performance specification 1.Appearance: no mechanical damage 2.Inductance shall be with ±20% of the initial value. b.Test condition 1.Temperature: 125°C ±2°C 2.Testing time: 1000±12hrs 3.Measurement: After placing at room ambient to		r 24 hours minimum	
	9-7 Electrostatic discharge test a. Performance specification 1.Appearance: no mechanical damage 2.Inductance shall be with ±20% of the initial value. b.Test condition 1.ESD voltage: 15k volts 2.Mode 1:150 pF/330 Ohm		. 24 Hodi 9 Hillimani	
	3.Mode 2:150 pF/330 Onm 3.Mode 2:150 pF/2000 Ohm REMARK ability tests can be adjusted according to customers' spe	cial requiremer	nts.	



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#### 10-5 PEELING STRENGTH OF COVER TAPE



Test condition

1. peel angle: 165°~180° vs carrier tape

2. peel speed: 300mm/min

## 11. Packaging

- 1. Tape & Reel packaging in component specification 6/8
- 2) Reel and a bag of desiccant shall be packed in Nylon or plastic bag
- 3) Maximum of 5 reels shall be packaged in a inner box
- 4) Maximum of 6 inner box shall be packaged in a outer box

### 12. Reel Label

Producing the goods label needs to indicate (1) Pb Free (2) RoHS Compliant

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#### 13. Storage

- 13-1The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Packages must be stored at 40°C or less and 70% RH or less.
- 13-2 The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust or harmful gas (hydrogen chloride, sulfurous acid gas or hydrogen sulfide).
- 13-3 Packaging material may be deformed if packages are stored where they are exposed to heat or direct sun—light.
- 13-4 Minimum packages, such as polyvinyl heat—seal packages shall not be opened until just before they are used.

  If opened, use the reels as soon as possible.
- 13-5 Solderability specified in component specification 4/8 shall be for 12 months from the date of delivery on condition that they are stored at the environment specified clause 13-1 & 13-2.

For those parts which passed more than 12 months shall be checked solderability before it is used.